



TECHNICAL PAPER PRESENTATION - 2024



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TECHNICAL PAPER PRESENTATION - 2024

The STEPCONE platform aims to showcase empirical research outcomes across diverse engineering domains, emphasizing the identification of research gaps and advancements in emerging areas of engineering and technology. The platform also encourages the examination of current scientific contributions relevant to engineering research. Research communication, encompassing both novel perspectives on traditional domains and cutting-edge technologies, is highly encouraged.

We invite full papers in the prescribed format from enthusiastic student researchers. Submissions are accepted either as a single-author contribution or as a collaborative effort with a maximum of two authors.

We look forward to receiving innovative research contributions that contribute to the dialogue on engineering advancements and further enrich the STEPCONE platform with valuable insights.

1. DETAILS

Registration fee per author: Rs.200/-

Maximum no of authors: 2 per paper

- 1. There is no basic registration fee. Only event registration fee
- 2. Participation certificates will be given to all
- 3. 20 % of papers will be published in journals with ISSN Number.
- 4. Best paper receives a Silver medal

2. GUIDELINES FOR PAPER PRESENTATION & SUBMISSION

A. Submission Guidelines:

- 1. **Abstract Length:** Please submit an abstract of 100-150 words, providing a concise overview of your research paper.
- 2. Submission Deadline: The deadline for abstract submission is February 5th, 2024.
- 3. Intimation of acceptance : on or before within 12 working hours after submission.

Full Paper Submission:

3. **Selected Candidates:** Those whose abstracts are shortlisted will be notified to submit the full paper.

4. **Full Paper Length:** The full paper should be between 2000-5000 words. IEEE format (Citation and Reference) should be submitted in hard copy to the organizers and the soft copy should be submitted at https://docs.google.com/forms/d/e/1FAIpQLSflgvUZBW-tBrG0sUo66Kxx3lTk4nsCCUCVmJGcbkbg4kj9Lg/viewform?usp=sf_link

Paper should be typed in "Times New Roman" font size "12" and for heading font size of "14" in bold.

Paper contents should be arranged in the following order but can be modified if discipline/nature of work demands:

- Title
- Abstract
- Keywords
- Introduction
- Materials & Methods
- Result and Discussion
- Conclusion
- References
- 5. Submission Deadline: Full papers must be submitted by February 11th, 2024, for consideration.
- 6. **Author Details:** Please include the following details in the order in your paper:
 - serial order for all authors
 - Current Year of Study
 - Branch
 - Institute Name and Address
 - E-Mail ID
 - Phone Number
- 7. **Corresponding Author:** One author should submit on behalf of the entire group and will be treated as the Corresponding Author.

Presentation:

- 8. **Presentation Duration:** Each participant should be prepared for a 10-minute presentation of their paper at the venue. (**need to share the presentation with paper ID as file name before the 14**th Feb 2024)
- 9. **Schedule:** The presentation schedule will be communicated in the reply email after the abstract selection process.

We encourage you to participate actively in this event and look forward to receiving your abstracts. Should you have any queries, feel free to reach out to us at [technicalpaper2024@gmail.com].



3. TECHNICAL PAPER PRESENTATION THEMES

3.1. Computer Science and Engineering, Artificial intelligence and machine learning, Artificial intelligence and Data Science.

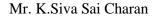
- 1. Cyber Security
- 2. Blockchain
- 3. AI & ML Recent Trends and Applications
- 4. DevOps in Software Engineering
- 5. AI in Data Science
- 6. Wireless Sensor Networks
- 7. Metaverse
- 8. Quantum computing
- 9. Natural Language Processing(NLP)
- 10. IOT-Based Security Mode
- 11. Augmented Reality/Virtual Reality
- 12. Quantum Computing/High Performance Computing
- 13. Holographic Data Storage
- 14. Cloud Computing-Ensuring Data Security
- 15. Neuromorphic Computing
- 16. IDMA The Future of Wireless Technology
- 17. 5G Technology and Its Implications
- 18. Exoskeletons in Rehabilitation and Industry
- 19. Web Technologies
- 20. Latest trends in Cyber Security

Ms.K. Jyotsna Dr. M. Satish Mr.CH.Sekhar Dr. A. V. Ramana Dr.K. Srividya

Student I/C Faculty SPOC-CSE Faculty SPOC-AI&DS/ML HOD-CSE HOD-AI&DS/ML

Information Technology

- 1. Machine learning algorithms
- 2. Predictive modelling
- 3. Computational complexity and optimization
- 4. Next-Generation Communication Technologies
- 5. Wireless Sensor Networks
- 6. Mobile computing & M-commerce
- 7. Virtualization and Cloud Computing
- 8. Data Privacy and Security
- 9. Blockchain Technology
- 10. IOT Privacy and Security Concerns, IOT forensic Science
- 11. Intelligent computing for intelligent systems
- 12. Machine learning and deep learning



Mr. Ch. Anil Kumar

Dr. V. Vasudha Rani

Student I/C

Faculty SPOC

HOD - IT

Electronics and Communication Engineering

- 1. Internet of Things (IoT) and its applications in various fields
- 2. 2. Artificial Intelligence (AI) and Machine Learning (ML) in signal processing, agriculture and other applications
- 3. 3. 6G and 5G technology its impact on communication systems
- 4. 4. Advanced antenna systems for wireless communication
- 5. 5. Image and video processing techniques for computer vision applications
- 6. 6. Biomedical signal processing and its applications in healthcare
- 7. 7. Embedded systems and their role in smart devices
- 8. 8. Green and sustainable electronics for energy-efficient systems
- 9. 9. VLSI design techniques for low-power and high-performance circuits
- 10. 10. Robotics and automation in industrial and everyday applications
- 11. 11.WIFI and LIFI
- 12. 12.wire less sensor network

Note: - Other relevant topics related to ECE will also be considered.

Mr.S.Venu

Dr.A.Siva Sangari

Dr. V. Jagan Naveen

Student I/C

Faculty SPOC

HOD - ECE

Electrical and Electronics Engineering

- 1. Renewable energy sources.
- 2. Battery management systems
- 3. Power electronics and it's applications
- 4. Power systems and it's applications
- 5. Wireless electricity
- 6. Health monitoring devices
- 7. IOT based home appliances
- 8. Control systems and it's applications
- 9. Smart grid technology.
- 10. Electric vehicles technology.
- 11. Irrigation control systems
- 12. AI for electrical applications
- 13. Energy efficient motors.
- 14. Cyber security for power system



Ms. I.Vidhyadhari

Dr. J S V Shiva Kumar

Dr.P. Ramana

Student I/C

Faculty SPOC

HOD - EEE

Civil Engineering

- 1. EBIM applications in structural engineering
- 2. New and advanced construction materials
- 3. Advanced Water proofing materials in structural applications
- 4. Building for Resilience: Designing Infrastructure to Withstand Natural Disasters
- 5. Building optimal design
- 6. Fossil fuels and renewable energy
- 7. Oil spills: Environmental Impact, Human Impact, Preventative Measures
- 8. Desalination:
- 9. Soil pollutions and treatment
- 10. Phytoremediation
- 11. Microbial Fuel Cells for Wastewater Treatment
- 12. Remote Sensing Application in Environmental Protection
- 13. Sustainable Water Management System
- 14. Air Quality Prediction using Machine Learning
- 15. Applications of IOT in Solid Waste Management
- 16. Marine geotechnics
- 17. Dams and tunnelling
- 18. Geosynthetics in soil stabilization
- 19. Geohazards and Risk Assessment
- 20. Sesimic control
- 21. Soil Dynamics
- 22. Soil Structure Interaction
- 23. Unsaturated Soil Mechanics
- 24. Unconventional materials and methods in soil stabilization
- 25. Liners in Municipal solid waste management
- 26. Sustainable Materials for pavement Design
- 27. Applications in Transportation Engineering
- 28. Intelligent Transport Systems
- 29. Asphalt products and properties

Ms.G.Lavanya

Student I/C

Mr. K. Naga Rajesh

Dr. G. Ganesh Prabhu

Faculty SPOC

HOD - CIVIL

Mechanical Engineering

- 1. Green Technologies
- 2. Sustainable Manufacture
- 3. Robotic and Human Machine Affairs
- 4. Industry 4.0
- 5. Energy Storage Technologies
- 6. Optimization Techniques for Mechanical Systems
- 7. Heat and Mass Transfer
- 8. Computational Fluid Dynamics
- 9. Nanofluid applications in convection heat transfer
- 10. Thermal management of Battery in electrical vehicles
- 11. Solar PV thermal systems
- 12. Micro heat exchangers
- 13. Smart Vehicle Design
- 14. Agile Manufacturing
- 15. Self-Healing Composite Materials
- 16. Recent advancement in design
- 17. Flexible manufacturing systems
- 18. Advanced manufacturing techniques
- 19. E-Waste
- 20. Machine learning applications in mechanical engineering

Topics related to contemporary engineering fields are also considered

Ms.K.Jasmitha Sai Dr. S.Ravi Babu

Dr. G. Sasi Kumar

Student I/C Faculty SPOC HOD - MECH

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